

First Call for Papers

MOC2021

26th MICROOPTICS CONFERENCE

<http://www.comemoc.com/moc2021/>

Sponsored by
The Japan Society of Applied Physics
(JSAP)

Organized by Microoptics Group



Technically co-sponsored by
IEEE Photonics Society

In cooperation with

The Optical Society (OSA)

The Optical Society of Japan

IEICE Electronics Society

IEEE Photonics Society Japan Chapter

IEEE Photonics Society Kansai Chapter

The Chemical Society of Japan

The Society of Polymer Science, Japan

The Laser Society of Japan

Optoelectronics Industry and Technology Development
Association

Japan Optomechatronics Association

Japan Photonics Council

Hamamatsu City

Shizuoka University

(Some organizations are under negotiation.)

Sep. 26 (Sun.) - Sep. 29 (Wed.), 2021

**Congress Center, ACT CITY Hamamatsu,
Shizuoka, Japan**

Paper Deadline: April 23 (Fri.), 2021

OBJECTIVE

The 26th MICROOPTICS CONFERENCE (MOC2021) will be held at Congress Center, ACT CITY Hamamatsu in Shizuoka Prefecture, Japan on September 26 – September 29, 2021. This conference is sponsored by the Japan Society of Applied Physics (JSAP) and organized by Microoptics Group and in cooperation with several academic societies and associations. The MOC2021 is intended to provide a central forum for an update and review of scientific and technical information covering a wide range of microoptics field from fundamental researches to systems and applications.

* Even though COVID-19 has a serious influence on the world, after careful consideration of the future situation, the MOC committee has decided to hold this conference mainly “on-site” in order to enhance international exchange among scientists and researchers.

CATEGORY

The category of the conference covers the following subjects of microoptics;

1. Theory, Modeling, and Design

Aberrations, Dispersion, Beam optics, Guided-wave optics, Gradient-index optics, Diffractive optics, Photonic band, Slow light, Near-field optics, Nonlinear optics, Thermo-optics, Plasmonics, Metal optics, Quantum optics/photonics, Biomimetic optics, Metaoptics, Simulation and system design, etc.

2. Materials and Fabrication

Semiconductors, Crystals, Dielectric materials, Polymers, Liquid crystals, Nonlinear materials, Composite materials, Nano-materials, Transparent conductors, Magneto-optic materials, Spin-materials, Metamaterials, Nanocarbons, etc. Micro- and nano-fabrication, Nano-imprint, Laser processing, Heterogeneous bonding, 3D printing, Optical manipulation, etc.

3. Measurement and Sensing

Spectroscopy, Interferometry, Reflectometry, Ultrafast measurement, 3D measurement, Quantum measurement, LiDAR, etc.

4. EO/OE and Active Devices

Lasers, LEDs, VCSELs, Array lasers, Amplifiers, Photo detectors, Terahertz devices, Optical imaging sensors, Solar cells, Energy harvesting devices, etc.

5. Passive Devices

Fibers, Waveguides, Multi/demultiplexers, Add-drop multiplexers, Branching and mixing components, Photonic crystals, Filters, Microlenses, Diffractive optical elements, Isolators, Polarizers, etc.

6. Dynamic and Functional Devices

MEMS, Switches, Modulators, Tunable devices, Wavelength converters, Nonlinear optical devices, Deflectors, Optical buffers, etc.

7. Integration, Packaging, and Si photonics

Monolithic and hybrid integration, Mounting and packaging, Micro-assembly, Wafer-level assembly, 3D integration, etc.

8. System and Design Conception

APPLICATION FIELD

The 26th MICROOPTICS CONFERENCE covers microoptics technologies in the following major topical fields;

A. Optical Communications

Photonic networks, Optical routing, Advanced multiplexing, LAN, FTTH, Wireless optical communication, etc.

B. Optical Interconnects

Chip/board/system interconnects, Active optical cable, etc.

C. Optoelectronic Equipment

Optical storages, Laser and LED printers, Smart sensors, Advanced cameras, Advanced microscopes, etc.

D. Optical Sensing and Processing

Optics for image recognition, Physical measurements, 3D measurements, Sensors and sensing systems, Security systems, Optical computing, Bio- and medical sensing, Tomography, etc.

E. Displays and Lighting

LCD, Laser/LED/EL displays, MEMS displays, 3D displays, Projection displays, μ -LED displays, Wearable displays, AR/VR-glass, head mounted displays, Flexible displays, Solid state lighting, Illuminations, Appearance design and control, etc.

F. New Applications and Emerging Technologies

Green photonics, Environmental and energy optics, Bio- and medical optics, Nano-photonics, Quantum systems, Next generation and intelligent microoptics, Car optics, Agricultural and fishery optics, Optical wireless power transmission, AI and IoT, etc.

SUBMISSION OF PAPERS

Original papers that have not been previously presented and that describe new technical contributions to the areas covered by the technical descriptions in the aforementioned category will be accepted for presentation. A detailed instruction will be available from the following Web site.

<http://www.comemoc.com/moc2021/>

Papers should be submitted electronically no later than **April 23 (Fri.), 2021**. Authors will be requested to submit a **2-page paper** written in English, including text, figures, tables, and references within a frame of 17 cm x 24 cm. The paper template will be available through the Web site.

POSTER SESSION

In addition to regular oral presentation sessions, a poster presentation session will be planned to stimulate detailed explanation and discussion. The author(s) of papers will be informed of the size of bulletin board for displaying summary, figures, tables, etc., when selected as poster papers.

POST-DEADLINE PAPER

A limited number of post-deadline papers will be accepted for presentation at post-deadline sessions. The latest significant results obtained after the regular deadline are most welcome.

PAPER PUBLICATION

Accepted papers will be published in **IEEE Xplore** in addition to the conference technical digest. The authors will also have a chance to publish an extended, full-length version of the

paper presented at MOC2021 in a **special issue of the JJAP**, which is an international journal published by the Japan Society of Applied Physics and IOP publishing. The special issue of the JJAP will be published in 2022.

PAPER AWARDS

The Best Paper Award will be given to several excellent contributed papers. Moreover, the Student Paper Award will be given to several excellent papers presented by students.

FINANCIAL SUPPORT FOR OVERSEAS STUDENTS

Limited financial support is considered for the presentations by students from overseas. Details will be announced in the Final Call for Papers.

OFFICIAL LANGUAGE

The official language of MOC2021 is English.

CONFERENCE VENUE

The MOC2021 will take place at Congress Center, ACT CITY Hamamatsu, Shizuoka, Japan. It is located adjacent to Hamamatsu Station, the gateway to the city of Hamamatsu.

Congress Center, ACT CITY Hamamatsu

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https://www.actcity.jp/pdf/actcity_pamphlet.pdf

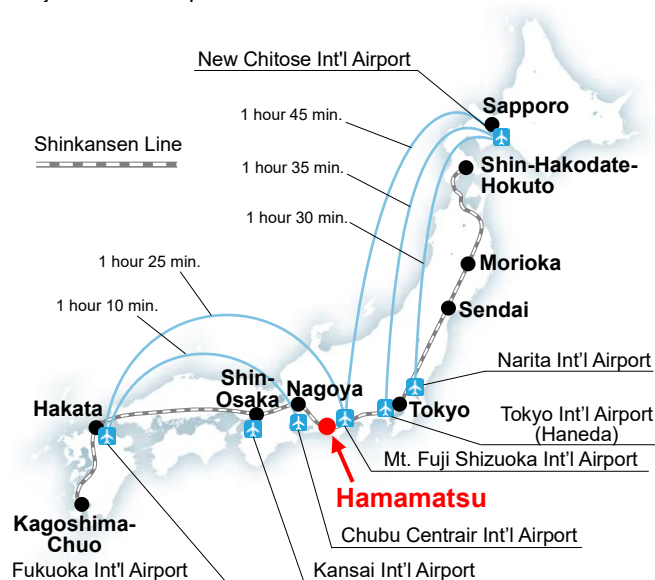


About Hamamatsu

Hamamatsu is the largest city in Shizuoka Prefecture and located about halfway between the two metropolitan cities of Tokyo and Osaka. There are many tourist attractions of great historical and cultural significance including famous temples, historical landmarks, and Lake Hamana. A wide range of activities are also available at Hamamatsu: bathing in hot springs, cycling, marine sports, and industrial tours unique to the "City of Manufacturing." As for food, visitors will no doubt be satisfied with local specialty foods including gyoza dumplings, mikan oranges (mandarin oranges), and fresh local seafood like eels, oysters, and puffer fish. For detail on sightseeing, visit <https://hamanako-tourism.com/en/>

ACCESS

Centrally located between Tokyo and Osaka, Hamamatsu is only about 90 minutes away from either of the cities by Shinkansen. ACT CITY, an event center offering direct Shinkansen access, can be easily reached on a day trip from major cities in Japan.



FURTHER INFORMATION

The final Call for Papers will be issued in January 2021. The latest information will be also presented on the web site:

<http://www.comemoc.com/moc2021/>

CONTACT

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